



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE75008-ESD	Issued	17. May 2021
MA#	MA005420565		
Package	PG-TSDSO-24-21	Weight*	111.73 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.881	1.68	1.68	16835	16835
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		142	
	non noble metal	zinc	7440-66-6	0.063	0.06		566	
	non noble metal	iron	7439-89-6	1.266	1.13		11328	
	non noble metal	copper	7440-50-8	51.392	46.00	47.20	459965	472001
wire	non noble metal	copper	7440-50-8	0.855	0.76	0.76	7649	7649
encapsulation	organic material	carbon black	1333-86-4	0.154	0.14		1378	
	plastics	epoxy resin	-	6.007	5.38		53760	
	inorganic material	silicondioxide	60676-86-0	45.178	40.44	45.96	404352	459490
leadfinish	non noble metal	tin	7440-31-5	2.820	2.52	2.52	25240	25240
plating	noble metal	silver	7440-22-4	1.279	1.14	1.14	11447	11447
glue	plastics	epoxy resin	-	0.143	0.13		1284	
	noble metal	silver	7440-22-4	0.676	0.61	0.74	6054	7338
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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